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1992

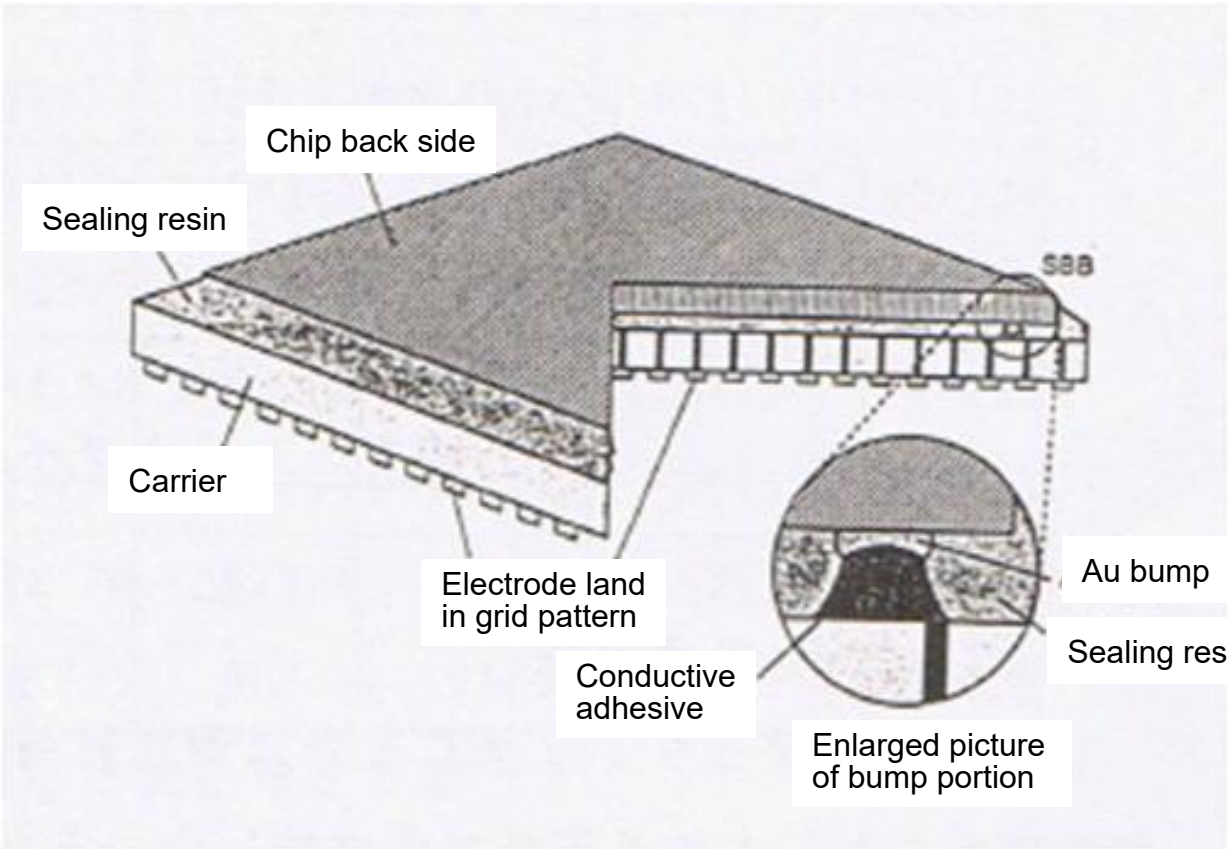
Start of mass production of LGA-type CSPs

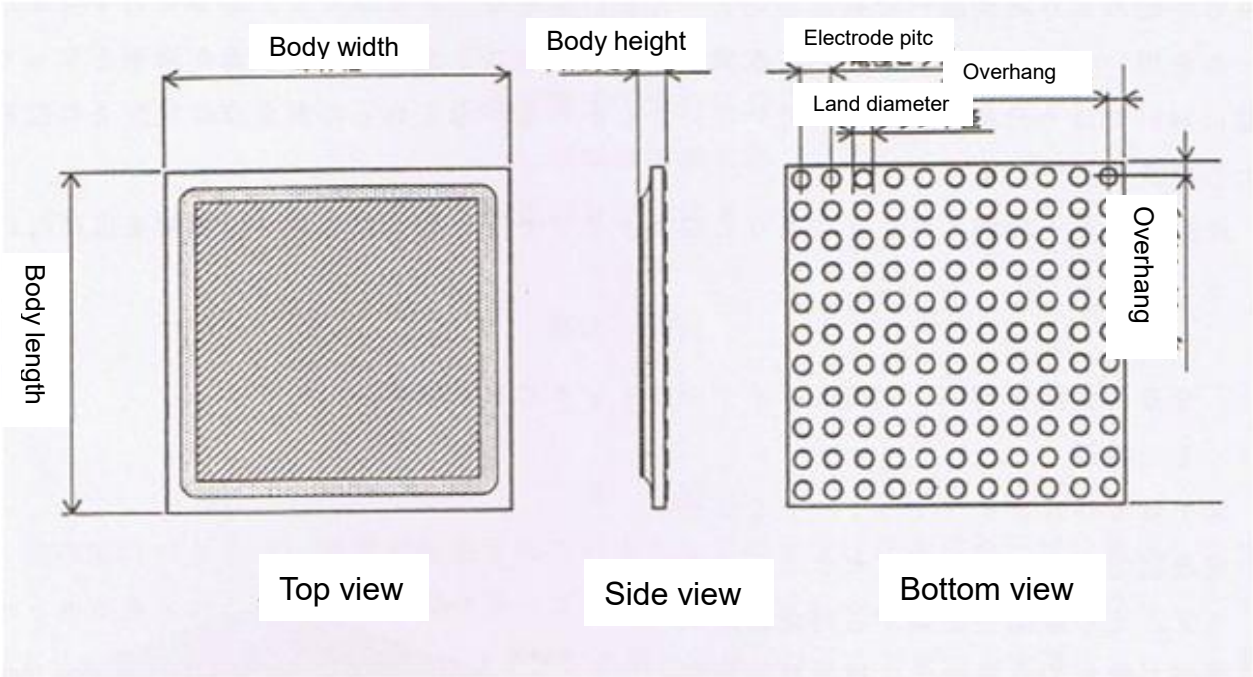
~ Packaging ~

In 1992, Matsushita Electronics started the mass production of CSP with Au wire stud bumps on the bonding pads of LSI which were then flip-chip connected to the connecting terminals provided on the ceramic substrate with conductive adhesive.

LSI connection terminals were provided on the surface of the ceramic substrate, and LGA (Land Grid Array) was arranged in the form of area array on the back surface. LSI is flip-chip connected to this board, and the periphery of the chip is sealed with sealing resin.

The figures below show a schematic of LGA structure and the package outline.





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